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**Field Device Integration (FDI) –
Part 4: FDI Packages**

**Intégration des appareils de terrain (FDI) –
Partie 4: Paquetages FDI**



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INTERNATIONAL
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ICS 25.040.40; 35.100

ISBN 978-2-8322-2640-7

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FIELD DEVICE INTEGRATION (FDI) –

Part 4: FDI Packages

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The text of this standard is based on the following documents:

CDV	Report on voting
65E/347/CDV	65E/424/RVC

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

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A list of all parts in the IEC 62769 series, published under the general title *Field Device Integration (FDI)*, can be found on the IEC website.

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FIELD DEVICE INTEGRATION (FDI) –

Part 4: FDI Packages

1 Scope

This part of IEC 62769 specifies the FDI Packages. The overall FDI architecture is illustrated in Figure 1. The architectural components that are within the scope of this document have been highlighted in this figure.

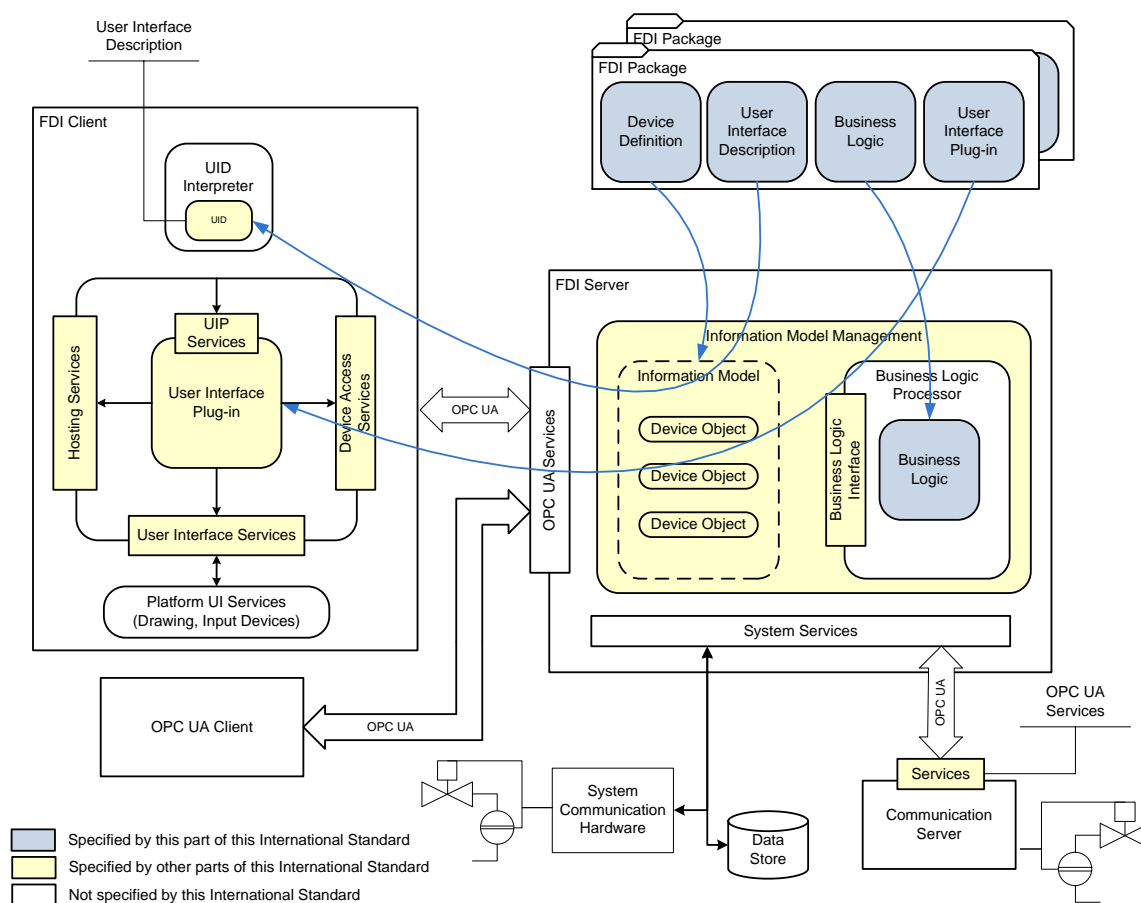


Figure 1 – FDI architecture diagram

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61804 (all parts), *Function blocks (FB) for process control and Electronic Device Description Language (EDDL)*